503900403 07/05/2016 PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3947055

11/03/2014

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	ASSIGNMENT		
CONVEYING PARTY DATA			
	Name	Execution Date	
WEI MA		11/03/2014	
WAI HUNG		11/03/2014	
FRANCIS GUILLEN GAMBOA		11/03/2014	
XIAOMING YU		11/03/2014	

DENNIS TAK KIT TONG

RECEIVING PARTY DATA

Name:	SAE MAGNETICS (H.K.) LTD.
Street Address:	SAE TECHNOLOGY CENTRE, 6 SCIENCE PARK EAST AVENUE, HONG KONG SCIENCE PARK, SHATIN, N.T.
City:	HONG KONG
State/Country:	HONG KONG

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15201519

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	SAE-1604-USCON
NAME OF SUBMITTER:	CHARLES S. HO
SIGNATURE:	/charles ho/
DATE SIGNED:	07/05/2016

Total Attachments: 5

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ASSIGN	IMENT	- Patent App	olication	[Docket Numb	er: SAE-1604-USCON
Whereas, the Assignor, comprising the following named inventors:						
ASSIGNOR(s)/ INVENTOR(s)	Wei Ma					
made an inventi	on entitled:	WAFER LEVEL MODULE HAVI			ICAL SUBA	SSEMBLY AND TRANSCEIVER
for which an app (Select one of the		Letters Patent of t	he United St	ates:		
🔲 🛛 was filed i	n the U.S. I	ntly herewith Patent and Tradem ation Serial No.: _	nark Office or	า	,	
		SAE Magnetics	(H.K.) Ltd.			
ASSIGNEE (Full Name, Add Country)	ress and	Park, Shatin, N.		Scien	ce Park East	Avenue, Hong Kong Science
	·.· ·	Hong Kong	·	· · ·		
is desirous of ac obtained therefo		entire right, title a	nd interest in	and t	o said inventi	on and the Letters Patent to be
Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto.						
Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.						
Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument.						
In witness whereof, this Assignment is executed on the day indicated below.						
	Typed o	r Printed Name		Sign	ature	Date
SIGNATURE	۱	Wei Ma	× ~	m	Ţ	× 3-11-2014

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KA LAP TONG X LAP * Witness to Assignor * Witness to Assignor

PATENT REEL: 039071 FRAME: 0230

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3-Nov-14

ASSIGNMENT - Patent Application Docket Number: SAE-1604-USCON						
Whereas, the Assignor, comprising the following named inventors:						
ASSIGNOR(s)/ INVENTOR(s)						
made an inventi	on entitled:	WAFER LEVEL P MODULE HAVING		PTICAL SUBASSEMBLY AN	ID TRANSCEIVER	
for which an app (Select one of the		Letters Patent of the	United States	::		
🗍 was filed i	n the U.S. F	ntly herewith Patent and Trademar ation Serial No.:	k Office on	1		
		SAE Magnetics (H	.K.) Lfd.			
ASSIGNEE (Full Name, Add Country)	lress and			nce Park East Avenue, Hor	ıg Kong Science	
		Hong Kong				
is desirous of ac obtained therefo		entire right, title and	interest in and	I to said invention and the Le	tters Patent to be	
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Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.						
Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument.						
In witness whereof, this Assignment is executed on the day indicated below.						
	Typed o	Printed Name	Się	gnature	Date	
SIGNATURE	w	ai Hung	×A	A	× 3-HOV-2014	
	KA * Witness t	LAP TONG	X * Witness to	Assignor	X 3-Neu-14	

PATENT REEL: 039071 FRAME: 0231

ASSIGNMENT - Patent Application Docket Number: SAE-1604-USCON					
Whereas, the Assignor, comprising the following named inventors:					
ASSIGNOR(s)/ INVENTOR(s) Francis Guillen Gamboa					
made an invention entitled: WAFER LEVEL PACKAGED OPTICAL SUBASSEMBLY AND TRANSCEIVER MODULE HAVING SAME					
for which an application for Letters Patent of the United States: (Select one of the following):					
 is executed concurrently herewith was filed in the U.S. Patent and Trademark Office on, as U.S. Patent Application Serial No.: 					
SAE Magnetics (H.K.) Ltd.					
ASSIGNEE (Full Name, Address and Country) SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T.					
Hong Kong					
is desirous of acquiring our entire right, title and interest in and to said invention and the Letters Patent to be obtained therefor,					
Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto.					
Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.					
Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument.					
In witness whereof, this Assignment is executed on the day indicated below.					
Typed or Printed Name Signature Date					
SIGNATURE Francis Guillen Gamboa X X 03 NW-201					
<u>KALAP, TONG</u> * Witness to Assignor * Witness to Assignor					

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ASSIGN	MENT	- Patent Appli	cation	Docket Number: SAE-16	04-USCON	
Whereas, the Assignor, comprising the following named inventors:						
ASSIGNOR(s)/ INVENTOR(s) Xiaoming Yu						
made an inventi	on entitled:	WAFER LEVEL P MODULE HAVING		PTICAL SUBASSEMBLY	AND TRANSCEIVER	
for which an app (Select one of the		Letters Patent of the	United State	s:		
🔲 🛛 was filed i	n the U.S. I	ntly herewith Patent and Trademar cation Serial No.:	k Office on			
• •		SAE Magnetics (H	.K.) Ltd.	•		
ASSIGNEE (Full Name, Add Country)	ress and			ence Park East Avenue, He	ong Kong Science	
	··· · · · · · · · · · · · · · · · · ·	Hong Kong				
is desirous of ac obtained therefo		entire right, title and	interest in an	d to said invention and the L	etters Patent to be	
One Dollar (\$1.0 acknowledged, / successors and for Letters Pater rights to claim pr	0), and for Assignor, ir assigns, th t for said in riority base	other good and value ntending to be legally le full and exclusive r nvention, including all	able consider bound, hereb ight, title and I divisions, co tters Patent, it	ssignee to Assignor of a sun ation, the receipt of which is by sells, assigns and transfe interest in and to said invent ntinuations, and continuation ncluding reissues, to be obta responding thereto.	hereby rs to Assignee, its tion, all applications ns-in-part thereof, all	
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	Typed o	r Printed Name	Si	gnature	Date	
SIGNATURE	Xia	oming Yu	× m	Kiluwing	× 3/Nalson	
	KA * Witness	LAT TONG.	X * Witness to	ap . Assignor	X 3-Nov-14	

* Witness to Assignor

ASSIGNMENT - Patent Application Docket Number: SAE-1604-USCON						
Whereas, the Assignor, comprising the following named inventors:						
ASSIGNOR(s)/ Dennis Tak Kit Tong INVENTOR(s)						
made an inventio	n entitled:	WAFER LEVEL I MODULE HAVIN		PTICAL SUBAS	SEMBLY AND TH	RANSCEIVER
for which an appl (Select one of the f		Letters Patent of th	e United States			
🔲 🛛 was filed in	the U.S. F	ntly herewith Patent and Tradema ation Serial No.:	ark Office on			
		SAE Magnetics (H.K.) Ltd.	· · · · · · · · · · · · · · · · · · ·		
ASSIGNEE (Full Name, Addr Country)	ess and	SAE Technology Park, Shatin, N.T		nce Park East /	Avenue, Hong Ko	ong Science
	.	Hong Kong				
is desirous of acc obtained therefor		entire right, title and	d interest in and	to said invention	n and the Letters I	Patent to be
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In witness whereof, this Assignment is executed on the day indicated below.						
	Typed o	Printed Name	Sig	gnature		Date
SIGNATURE	Dennis	Tak Kit Tong	×	\sim	X	3-Nov-Jal)
-	KA * Witness t	LAP TONG	X * Witness to	ر Asslignor	X	3-Nov-14

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PATENT REEL: 039071 FRAME: 0234

RECORDED: 07/05/2016